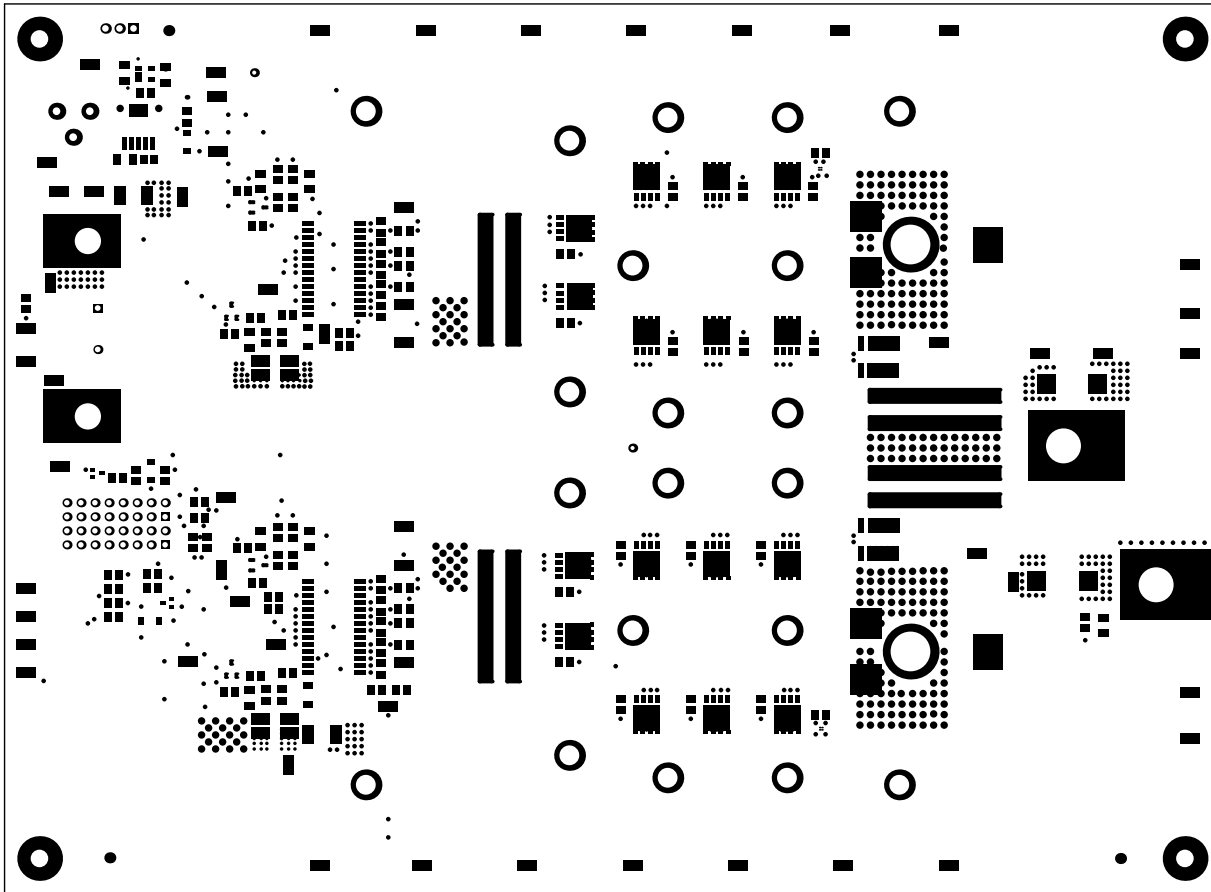
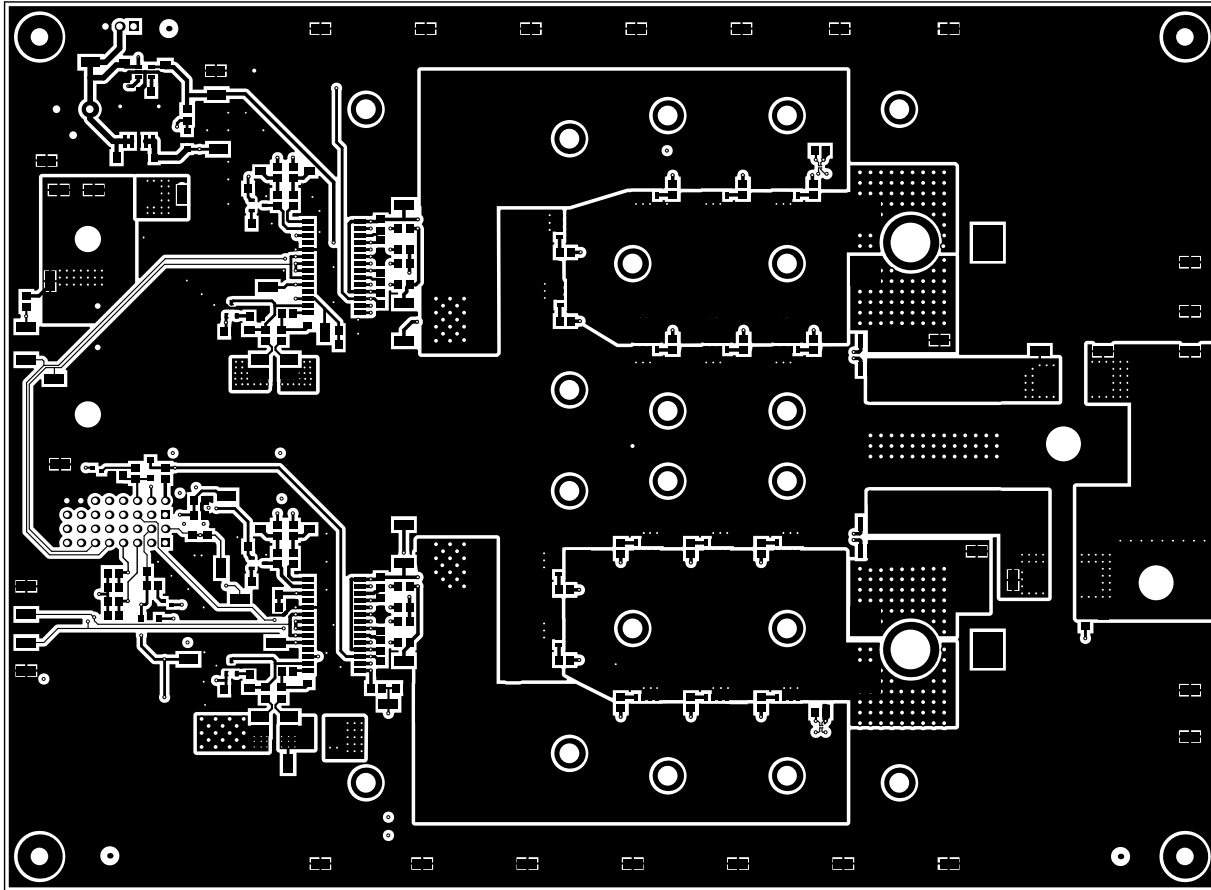


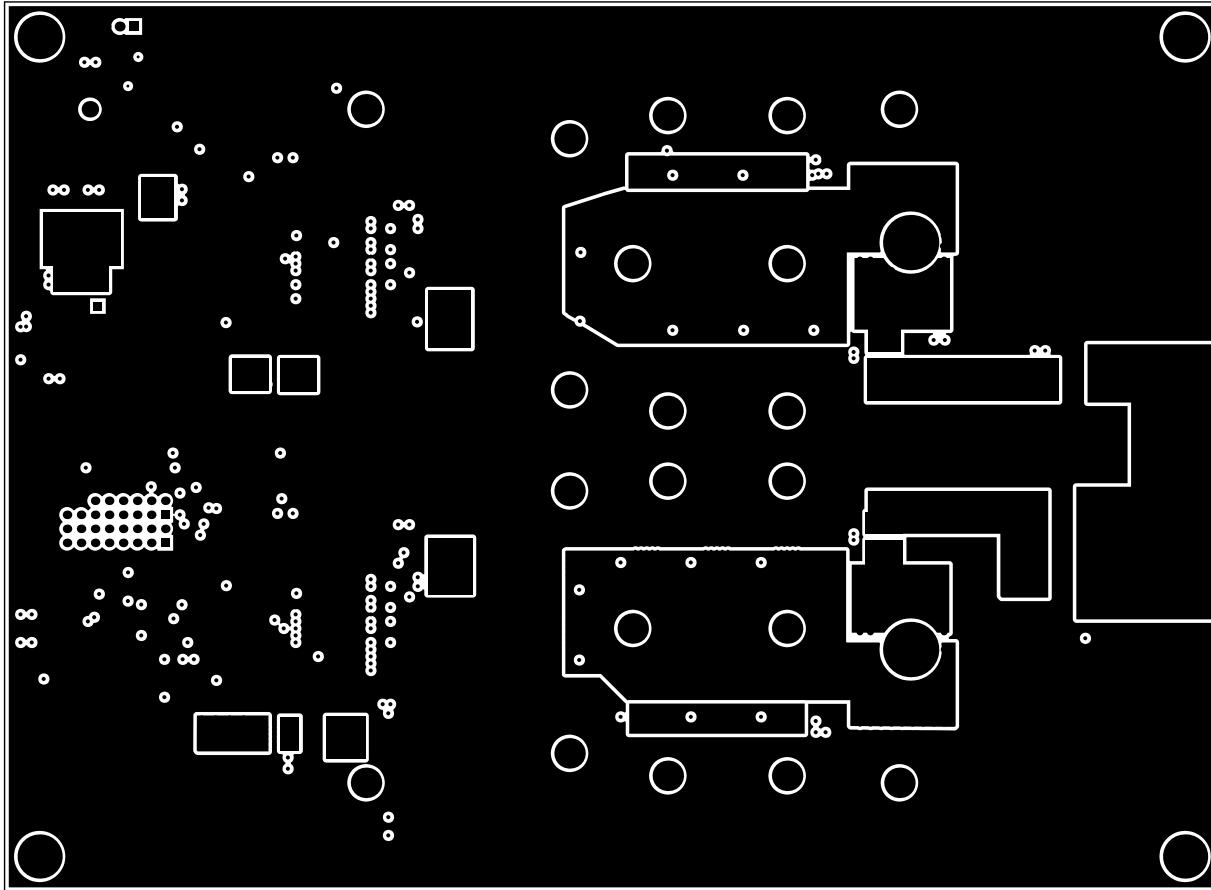
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/18/2015 2:32:00 PM	TEXAS INSTRUMENTS	



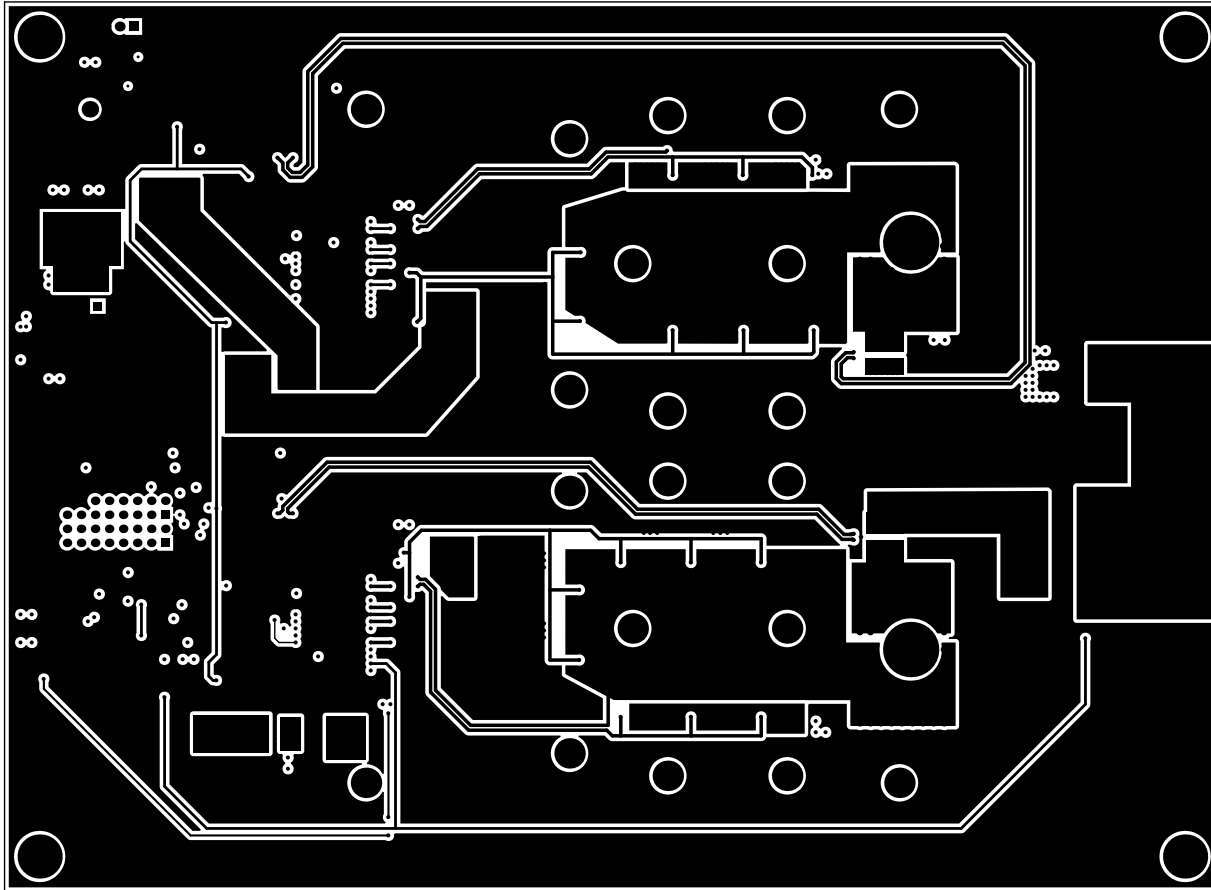
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/18/2015 2:32:01 PM	TEXAS INSTRUMENTS	



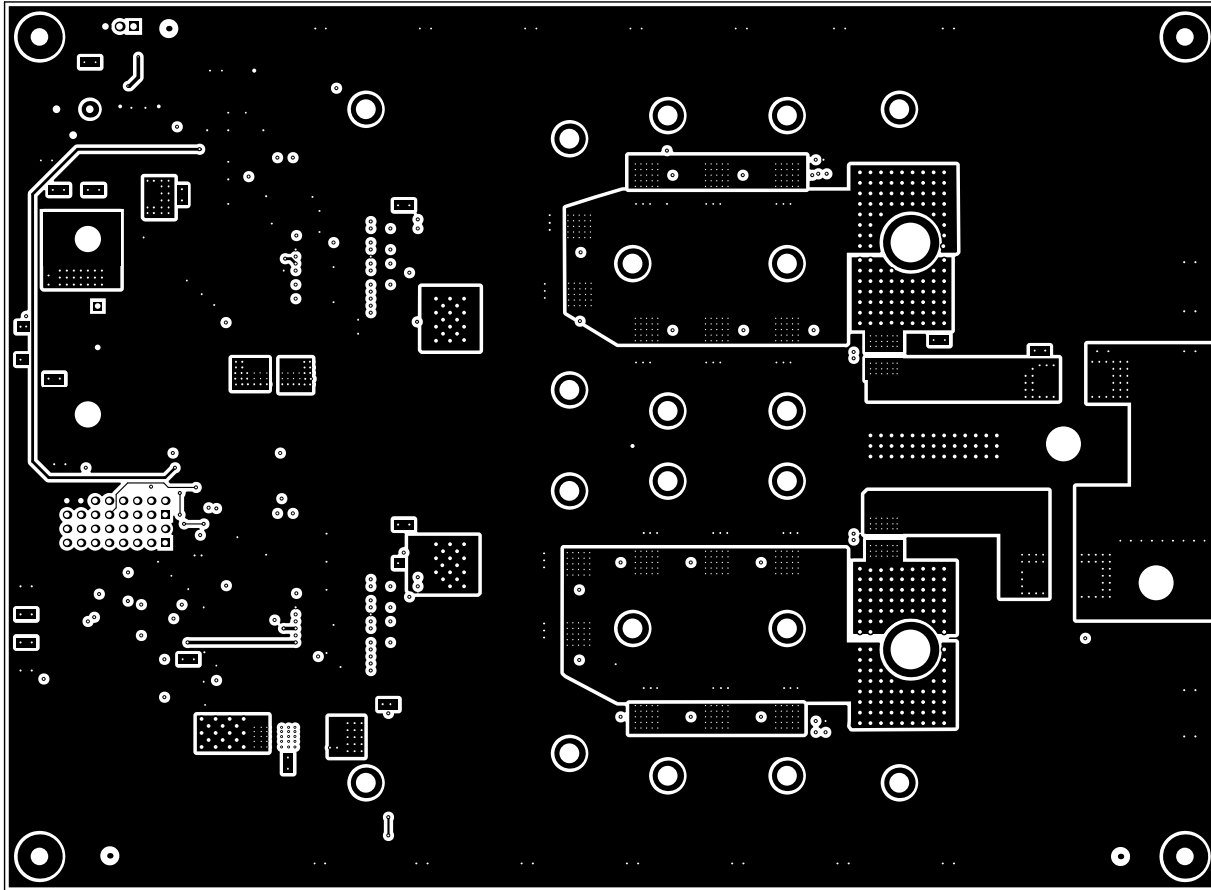
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/18/2015 2:32:01 PM	TEXAS INSTRUMENTS	



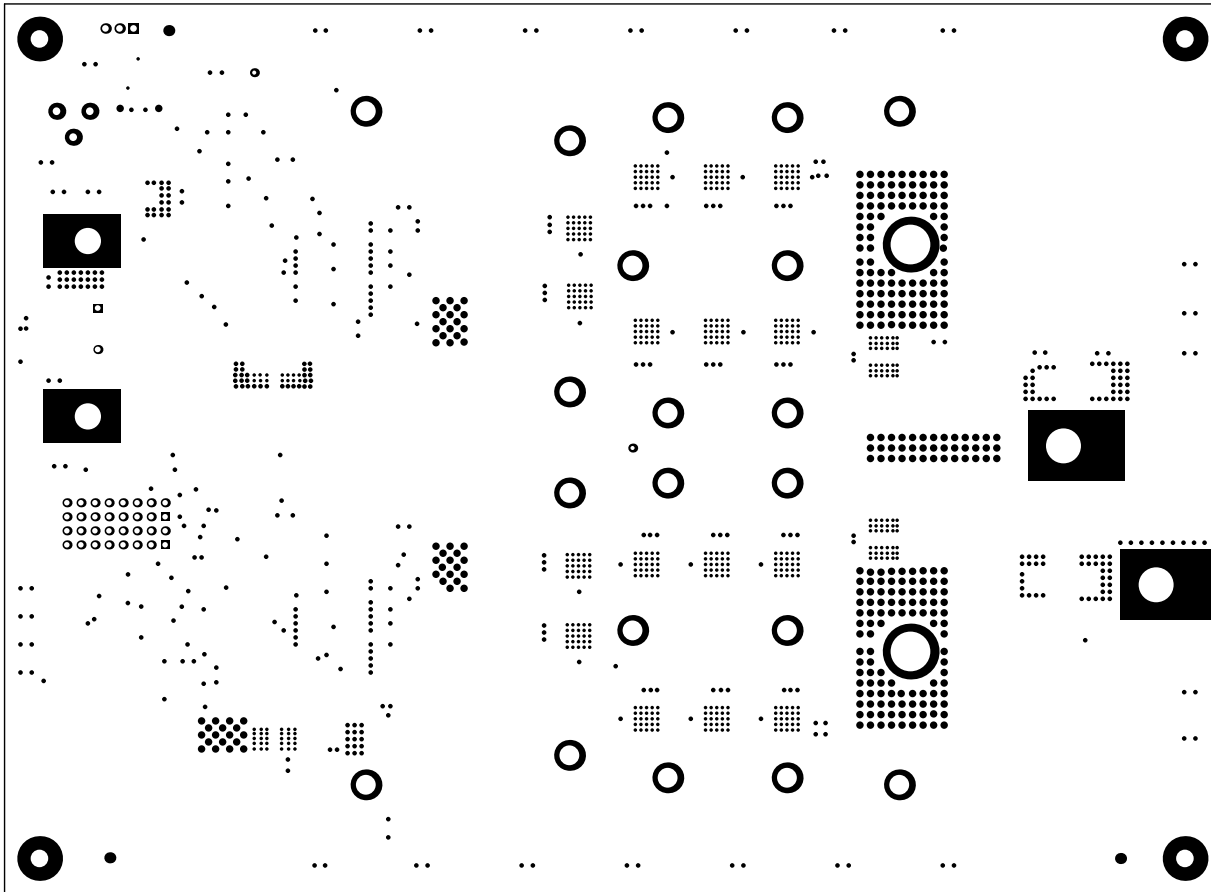
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = MI Board Outline			
PLOT NAME = Mid Layer 1	GENERATED : 9/18/2015 2:32:02 PM	TEXAS INSTRUMENTS	



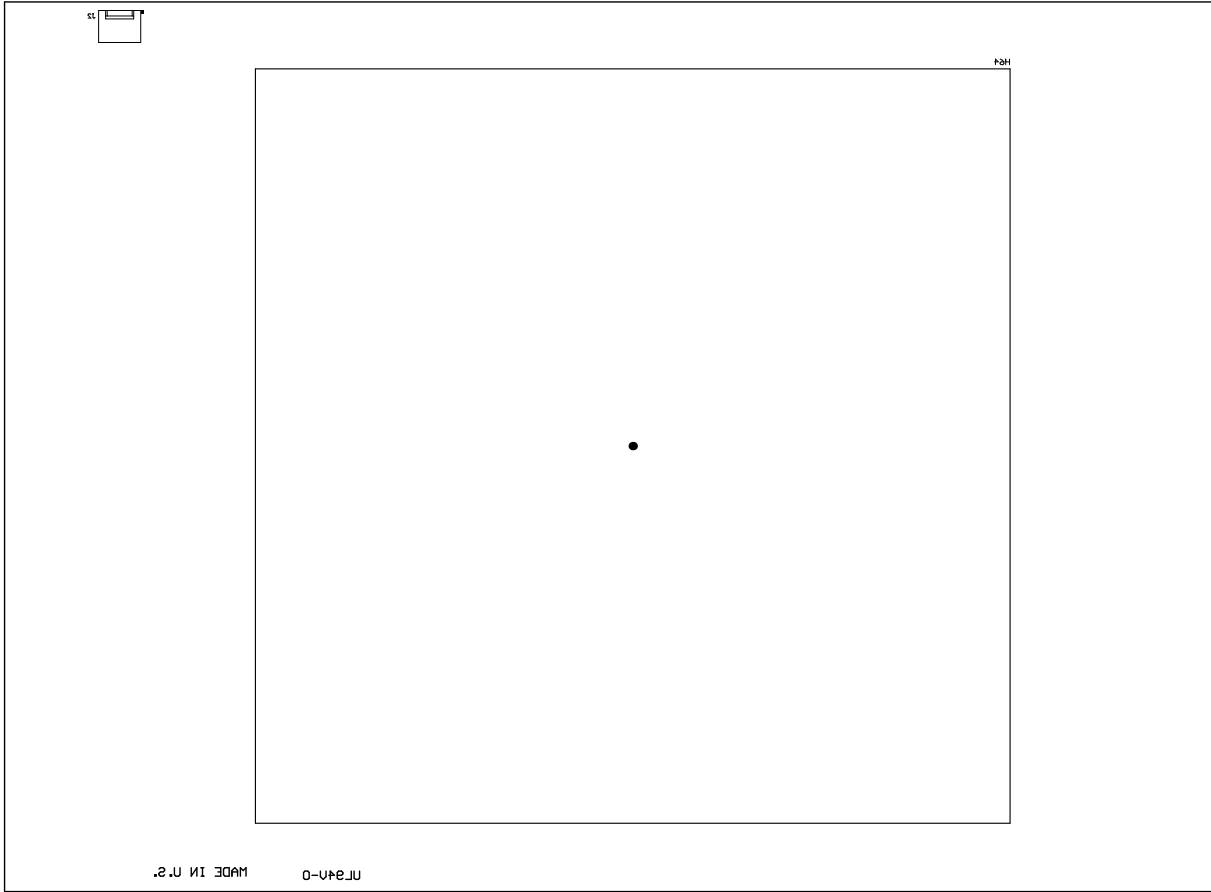
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = MI Board Outline			
PLOT NAME = Mid Layer 2	GENERATED : 9/18/2015 2:32:02 PM	TEXAS INSTRUMENTS	



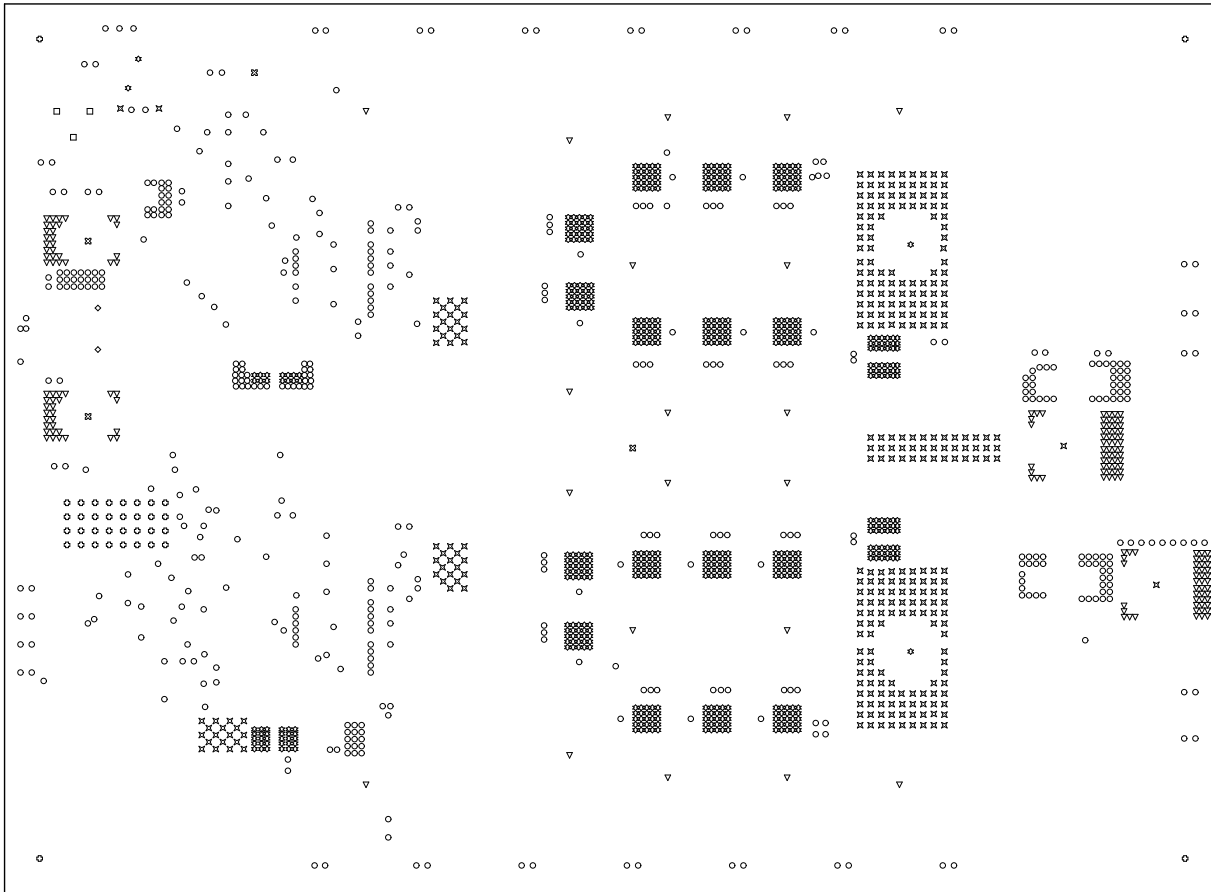
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/18/2015 2:32:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/18/2015 2:32:03 PM	TEXAS INSTRUMENTS	



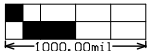
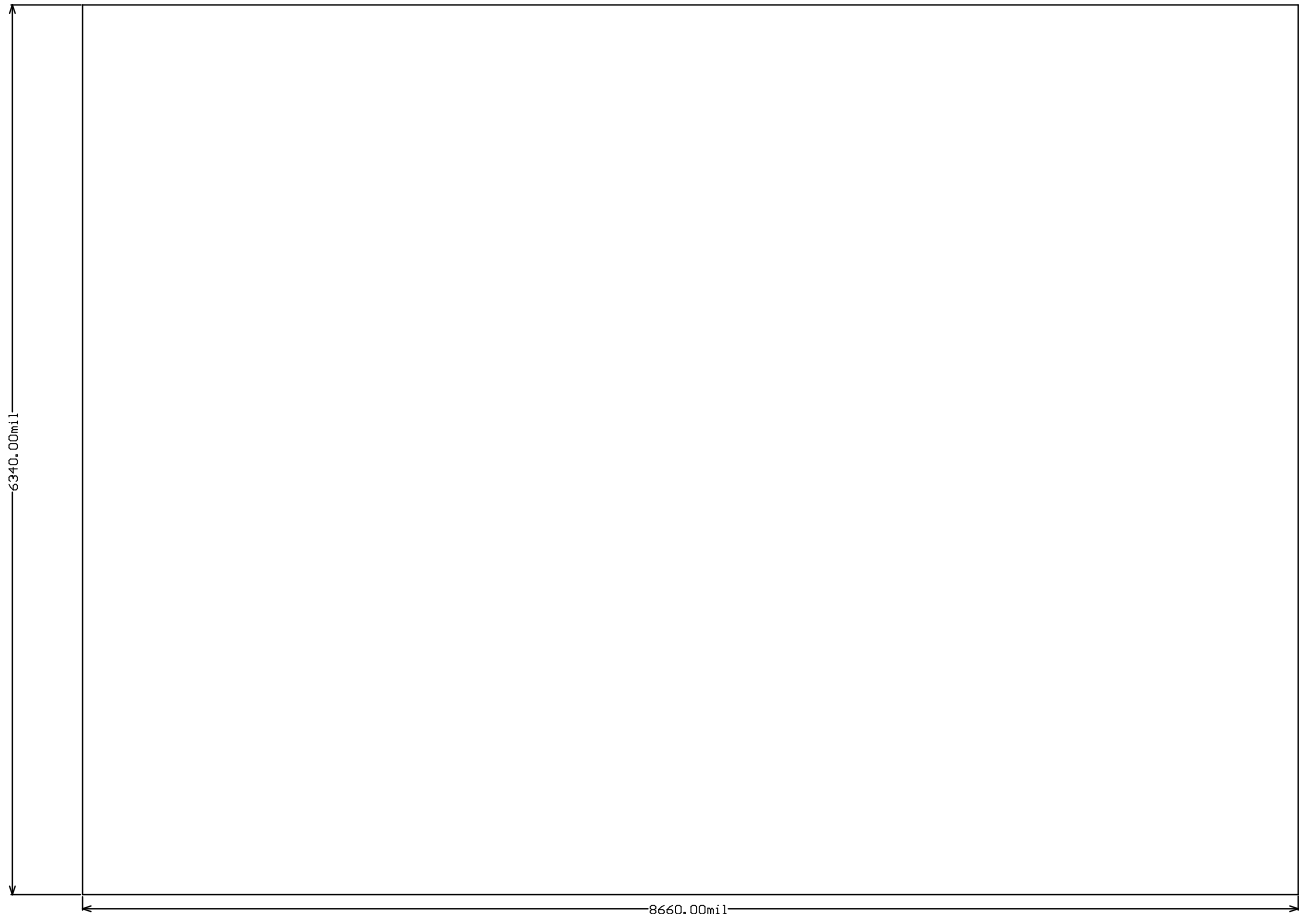
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/18/2015 2:32:04 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
⊗	518	10mil (0.254mm)	PTH	Round
○	479	15mil (0.381mm)	PTH	Round
▽	172	16mil (0.406mm)	PTH	Round
⊗	303	28mil (0.711mm)	PTH	Round
⊗	2	30mil (0.762mm)	PTH	Round
○	32	40.945mil (1.04mm)	PTH	Round
◇	2	41.339mil (1.05mm)	PTH	Round
○	3	47.244mil (1.2mm)	PTH	Round
□	3	55.118mil (1.4mm)	PTH	Round
◇	4	125.984mil (3.2mm)	PTH	Round
▽	20	141.732mil (3.6mm)	PTH	Round
⊗	2	188mil (4.775mm)	PTH	Round
⊗	2	250mil (6.35mm)	PTH	Round
⊗	2	283.465mil (7.2mm)	PTH	Round
1544 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/18/2015	2:32:04 PM	TEXAS INSTRUMENTS



1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: .PRJ_Number	REV: .PCB_Rev	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/18/2015 2:32:05 PM	TEXAS INSTRUMENTS	

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